



PAST TTTC EVENTS

8th IEEE International Workshop on Silicon Debug and Diagnosis—SDD 2012
8–9 November 2012
Anaheim, CA
<http://sdd.ttc-events.org/12/index.html>

Troubleshooting how and why systems and circuits fail is important and is rapidly growing in industry significance. Debug and diagnosis may be needed for yield improvement, process monitoring, correcting the design function, failure mode learning for R&D, or just getting a working first prototype. This detective work is, however, very tricky. Sources of difficulty include circuit and system complexity, packaging, limited physical access, shortened product creation cycle and time-to-market. New and efficient solutions for debug and diagnosis have a much needed and highly visible impact on productivity.

SDD 2012 will be held in Anaheim, CA. It is the eighth of a series of highly successful technical workshops that consider issues related to debug and diagnosis of semiconductor circuits and systems—from prototype bring-up to volume production.

3rd IEEE International Workshop on Testing Three-Dimensional Stacked Integrated Circuits—3D-Test
8–9 November 2012
Anaheim, CA
<http://3dtest.ttc-events.org/>

The 3D-TEST Workshop focuses exclusively on test of and design-for-test for three-dimensional stacked ICs (3D-SICs), including Systems-in-Package (SiP), Package-on-Package (PoP), and especially 3D-SICs based on Through-Silicon Vias (TSVs).

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While 3D-SICs offer many attractive advantages with respect to heterogeneous integration, smaller form-factor, higher bandwidth and performance, and lower power dissipation, there are many open issues with respect to testing such products. The 3D-TEST Workshop offers a forum to present and discuss these challenges and (emerging) solutions among researchers and practitioners alike.

3D-TEST will take place in conjunction with the IEEE International Test Conference (ITC) and is sponsored by the Test Technology Technical Council (TTTC) of IEEE Computer Society.

17th IEEE International High Level Design Validation and Test Workshop—HLDVT
9–10 November 2012
Huntington Beach, CA
<http://hldvt.com/>

The 17th IEEE International High Level Design Validation and Test Workshop (HLDVT) advances research in validation and test methodologies for integrated circuits and systems. The workshop focuses on addressing the current bottlenecks in validation and test of complex and heterogeneous systems by both employing high-level specifications (such as register transfer level, behavioral and system-level models) and developing associated tools, techniques and methodologies to enable drastic reduction in overall design, validation and test effort. The workshop provides a forum for leaders in both industry and academia to advance the means for validating, debugging, synthesizing, and testing complex systems in a way that opens new avenues to overcome current validation and test challenges.

UPCOMING TTTC EVENTS

14th IEEE Latin-American Test Workshop (LATW)
2–5 April 2013
Cordoba, Argentina
<http://tima.imag.fr/conferences/latw2013/>

The IEEE Latin-American Test Workshop (LATW) provides an annual forum for test and fault-tolerance professionals and technologists from all over the world and, in particular, from Latin America to present and discuss various aspects of system, board, and component testing and fault-tolerance with design, manufacturing and field considerations in mind. Presented papers are also published in the IEEE Xplore Digital Library. The best papers of the 14th IEEE LATW will be invited to resubmit to the IEEE Design and Test of Computers, *Journal of Electronic Testing: Theory and Applications (JETTA)*, and the *Journal of Low Power Electronics (JOLPE)*.

International Design and Test Symposium
15–17 December 2012
Doha, Qatar
<http://idtsymposium.org/>

The International Design and Test Symposium explores emerging challenges and novel concepts in design, automation and test of electronic products ranging from integrated circuits through multichip modules and printed circuit boards to full systems and microsystems, as well as examining the methodologies and tools used in the design, verification and silicon debug of such products. IDT provides a unique forum to discuss best practices and novel approaches in design, automation and test in the Middle East and Africa (MEA) region.

IDT'12 will take place in Doha, Qatar. The symposium is initiated and sponsored by the IEEE Computer Society Test Technology Technical Council and the 2012 edition is organized by Texas A&M University at Qatar.

Newsletter Editor's Invitation

I would appreciate input and suggestions about the newsletter from the test community. Please forward your ideas, contributions, and information on awards, conferences, and workshops to Theocharis (Theo) Theocharides, Department of Electrical and Computer Engineering, University of Cyprus, 75 Kallipoleos Avenue, P.O. Box 20537, Nicosia, 1678, Cyprus; ttheocharides@ucy.ac.cy.

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